Momentive Performance Materials provides leading-edge silicone technologies to help meet performance and productivity challenges in a wide range of automotive and electronic applications.

Momentive’s dielectric potting and encapsulation materials are excellent candidates to consider to protect electronic components from moisture and harmful contaminants. These materials help provide stress relief protection to circuits from thermal, vibration, and mechanical stress. Momentive offers a range of materials including one and two part products and specialized grades that can provide thermal conductivity, flame retardancy, and low volatiles.

**Key Features**
- Temperature resistance
- Low modulus, good dampening properties
- Low viscosity
- Very fast cure
- High dielectric strength
- Self healing gels

**Typical Benefits**
- Thermal and mechanical stress protection
- Easily flows around components
- Productivity, high outputs
- Reliability
- Probe testable

**Potential Applications**
- ECU potting
- Air flow mass meter
- Sensor potting
- LED encapsulants
### Typical Physical Properties

(Selected grades only; please contact us for material selection support)

<table>
<thead>
<tr>
<th>Product</th>
<th>System (1)</th>
<th>Ratio (w/w)</th>
<th>Cure Time</th>
<th>Color</th>
<th>Type</th>
<th>Viscosity (Pa·s)</th>
<th>Feature</th>
</tr>
</thead>
<tbody>
<tr>
<td>TSE3051</td>
<td>AC, 1K</td>
<td>n.a.</td>
<td>1 h @ 150°C</td>
<td>Clear</td>
<td>Gel</td>
<td>0.7</td>
<td>1 Part - Easy handling</td>
</tr>
<tr>
<td>TSE3070</td>
<td>AC, 2K</td>
<td>1:1</td>
<td>0.5 h @ 70°C</td>
<td>Clear</td>
<td>Gel</td>
<td>0.8</td>
<td>Excellent vibration damping</td>
</tr>
<tr>
<td>TSE3032</td>
<td>AC, 2K</td>
<td>10:1</td>
<td>1 h @ 100°C</td>
<td>Clear</td>
<td>Rubber</td>
<td>4</td>
<td>Non bonding</td>
</tr>
<tr>
<td>TSE3033</td>
<td>AC, 2K</td>
<td>1:1</td>
<td>30 min @ 150°C</td>
<td>Clear</td>
<td>Rubber</td>
<td>1</td>
<td>Self bonding</td>
</tr>
<tr>
<td>TSE331K-EX</td>
<td>AC, 2K</td>
<td>1:1</td>
<td>10 min @ 100°C</td>
<td>Dark grey</td>
<td>Rubber</td>
<td>3</td>
<td>UL94 - V0. Thermal conductive</td>
</tr>
<tr>
<td>TSE3251</td>
<td>AC, 1K</td>
<td>n.a.</td>
<td>1 hr @ 150°C</td>
<td>White</td>
<td>Rubber</td>
<td>8.5</td>
<td>1K - Easy handling</td>
</tr>
<tr>
<td>TSE3667</td>
<td>CC, 2K</td>
<td>100:8</td>
<td>24 hr @ RT</td>
<td>Dark grey</td>
<td>Rubber</td>
<td>3</td>
<td>Low temp adhesion, UL94 V-0, good deep section cure</td>
</tr>
<tr>
<td>RTV11</td>
<td>CC, 2K</td>
<td>Variable</td>
<td>24 hr @ RT</td>
<td>White</td>
<td>Rubber</td>
<td>11</td>
<td>FDA compliant (2), deep section cure possible</td>
</tr>
<tr>
<td>TSE3660</td>
<td>CC, 2K</td>
<td>100:8</td>
<td>24 hr @ RT</td>
<td>Light blue</td>
<td>Rubber</td>
<td>3</td>
<td>Low temp adhesion, good deep section cure, UL-94 HB</td>
</tr>
</tbody>
</table>

(1) AC = Addition Cure, CC = Condensation Cure
(2) Compositionally compliant with the requirements of 21 CFR 177.2600 - Rubber articles intended for repeated use have been found, through testing of a representative sample, to meet the extractives limitations in 21 CFR 177.2600(e) and/or (f). It is the responsibility of the user to determine that the final product complies with the extractive limitations and other requirements of 21 CFR 177.2600 under their specific manufacturing procedures.

Typical properties are average data and are not to be used as or to develop specifications.

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**For more information and sampling inquiries, please visit momentive.com/CustomerService**